

# Chip Scale Review®

ChipScaleReview.com

The Future of Semiconductor Packaging

## 2019 Editorial Calendar

<i>(Editorial close date: 6/15)</i>	July • August	Industry Events * indicates show distribution
High reliability materials		<ul style="list-style-type: none"> <li>• <b>ICEPT 2019</b> Shanghai, China (Aug 11-15)</li> <li>• <b>SEMICON Taiwan *</b> Taipei, Taiwan (Sept 18-20)</li> <li>• <b>European MEMS &amp; Sensors Summit</b> Grenoble, France (Sept 19-21)</li> <li>• <b>European Imaging &amp; Sensors Summit</b> Grenoble, France (Sept 19-21)</li> </ul>
Metal-based wafer-level and 3D printed packaging		
Temporary bonding for high temperature processing of thin glass		
Chip-package-board co-design		
Coaxial socket technology		
MEMS & Sensors		
Large-area fan-out processing		

**Ad Space Close Jun 30 - Ad Materials Close Jul 7**

<i>(Editorial close date: 7/20)</i>	September • October	Industry Events * indicates show distribution
Effective, Scalable EMI Protection		<ul style="list-style-type: none"> <li>• <b>SMTA International *</b> Rosemont, IL (October 24-25)</li> <li>• <b>IWLPC-International Wafer-Level Packaging Conference &amp; Exhibition *</b> San Jose, CA (Oct 22-24)</li> <li>• <b>IMPACT</b> Taipei, Taiwan (October 24-26)</li> <li>• <b>TestConX China 2019</b> Suzhou, China (Oct 23) Shenzhen, China (Oct 25)</li> <li>• <b>International Test Conference (ITC)</b> Phoenix, AZ (Oct 28- Nov 2)</li> <li>• <b>SEMI International Technology Partners Conference (ITPC)</b> Maui, Hawaii (Nov 4-7)</li> <li>• <b>SEMICON Europa / Productronica</b> Munich, Germany (Nov 12-16)</li> </ul>
Embedded RDL		
High density flip-chip and advanced CSP		
High-resolution 3D X-ray metrology		
Advanced substrates and embedded packaging		
High density advanced packaging (HDAP) design		
Direct-placement process for LED's		
Inspection strategies		
High density advanced packaging design		

**Ad Space Close Sep 8 - Ad Materials Close Sep 15**

<i>(Editorial close date: 9/21)</i>	November • December	Industry Events * indicates show distribution
Collective bonding for heterogeneous integration		<ul style="list-style-type: none"> <li>• <b>EPTC 2019 *</b> Singapore (Dec 3-6)</li> <li>• <b>MEPTEC: Heterogeneous Integration Symposium</b> Milpitas, CA (TBD)</li> <li>• <b>SEMICON Japan</b> Tokyo, Japan (Dec 11-13)</li> <li>• <b>SEMI European 3D Summit *</b> Dresden, Germany (TBD)</li> <li>• <b>SEMICON Korea 2020</b> Coex, Seoul, Korea (Feb 5-7, 2020)</li> </ul>
Cooling solutions for hi-density chips		
Advanced eWLB for mmWave applications		
High temperature survivability & the processes it allows		
Package assembly design kits		
Integration		
Direct-placement process LED's		
TSV and RDL technologies, the road ahead		

**Ad Space Close Nov 3 - Materials Close Nov 10**

For ad inquiries: [ads@chipscalereview.com](mailto:ads@chipscalereview.com) - For editorial inquiries [editor@chipscalereview.com](mailto:editor@chipscalereview.com)

Notes: Editorial calendar topics and distribution are subject to change without notice and are contingent on logistics and magazine production.  
Haley Publishing Inc. 2019 All rights reserved. Rev: CSR-EC-021119